



Material Content Data Sheet



Sales Product Name		ICL8002G		Issued		25. September 2017		
MA#		MA001054590						
Package		PG-DSO-8-42		Weight*		81.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.247	1.53	1.53	15284	15284
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.035	0.04		432	
	non noble metal	iron	7439-89-6	0.705	0.86		8639	
wire	non noble metal	copper	7440-50-8	28.624	35.08	35.99	350796	359975
	noble metal	gold	7440-57-5	0.170	0.21	0.21	2083	2083
	encapsulation	organic material	carbon black	1333-86-4	0.148	0.18		1812
plastics		epoxy resin	-	4.780	5.86		58577	
	inorganic material	silicondioxide	60676-86-0	44.347	54.35	60.39	543497	603886
leadfinish	non noble metal	tin	7440-31-5	0.814	1.00	1.00	9974	9974
plating	noble metal	silver	7440-22-4	0.084	0.10	0.10	1034	1034
glue	plastics	acrylic resin	-	0.127	0.16		1553	
	noble metal	silver	7440-22-4	0.507	0.62	0.78	6211	7764
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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